

# (19) United States

## (12) Patent Application Publication (10) Pub. No.: US 2023/0230966 A1 **CHANG**

Jul. 20, 2023 (43) **Pub. Date:** 

### (54) ELECTRONIC PACKAGE AND **ELECTRONIC DEVICE**

(71) Applicant: Advanced Semiconductor

Engineering, Inc., Kaohsiung (TW)

Wei-Hao CHANG, Kaohsiung (TW) Inventor:

Assignee: Advanced Semiconductor

Engineering, Inc., Kaohsiung (TW)

Appl. No.: 17/576,822

(22) Filed: Jan. 14, 2022

### **Publication Classification**

(51) Int. Cl.

H01L 25/16 (2006.01)H01L 31/12 (2006.01)H01L 31/0216 (2006.01)

H01L 23/31 (2006.01)H05K 1/02 (2006.01)H05K 1/11 (2006.01)

(52)U.S. Cl.

CPC ...... H01L 25/167 (2013.01); H01L 31/12 (2013.01); H01L 31/02164 (2013.01); H01L 23/3121 (2013.01); H05K 1/028 (2013.01); H05K 1/115 (2013.01); H05K 2201/10121 (2013.01)

#### (57) ABSTRACT

The present disclosure provides an electronic package. The electronic package includes a substrate, a first component disposed on the substrate and configured to detect an external signal, and an encapsulant disposed on the substrate. The electronic package also includes a protection element disposed on the substrate and physically separating the first device from the encapsulant and exposing the first device. The present disclosure also provides an electronic device.

la

